

Towards *in-process* Materials Characterization in Laser-based Metal Additive Manufacturing

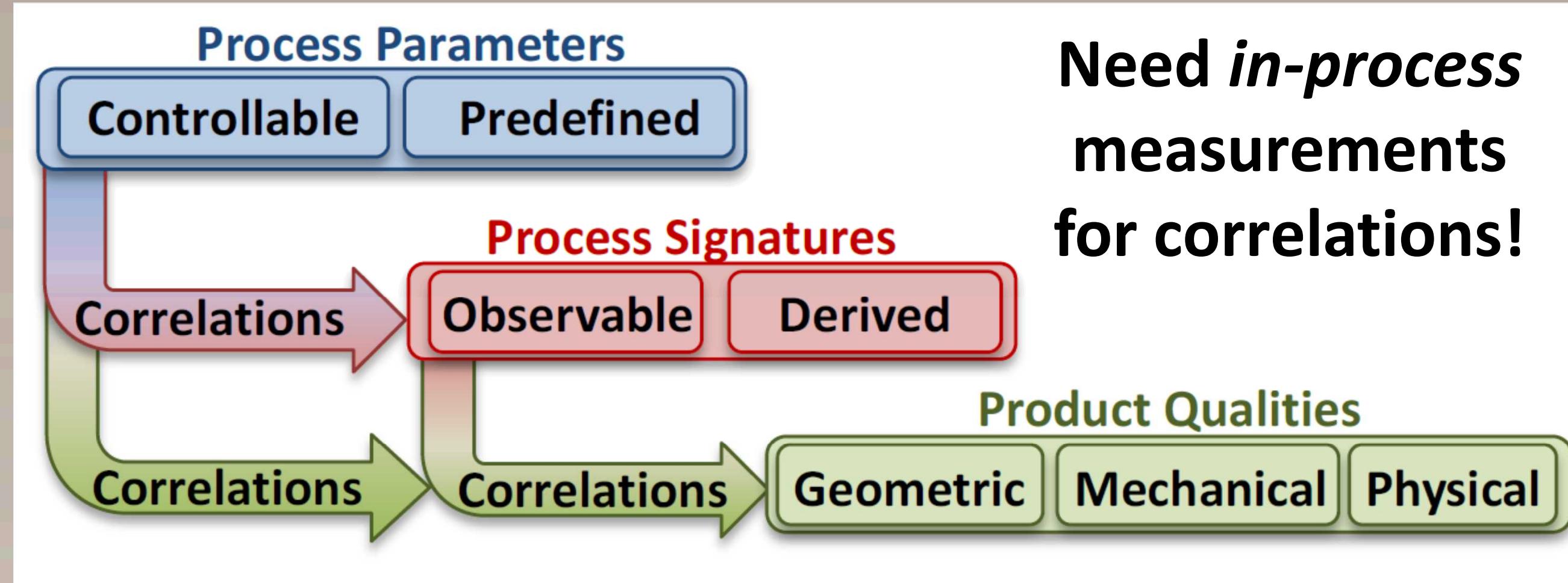
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Motivation

In-process materials characterization would enable closed-loop quality control, in-situ determination of material properties, and provide microstructural control...

– NIST, Measurement Science Roadmap for Metal-Based Additive Manufacturing (2013)



“Process parameters along with signatures in general have not yet been directly related to product quality...”

– NIST, Measurement Science Needs for Real-time Control of AM Powder Bed Fusion Processes (2015)

Parameters	Signatures		Qualities
<u>Tunable:</u>	<u>Melt Pool</u>	<u>Solidified Material</u>	<u>Geometric:</u> Dimensional Deviations
1. Laser power, velocity and diameter	Temperature, profile and history	Layer-by-layer Geometric Irregularities	<u>Mechanical:</u> Strength Hardness Toughness Fatigue Life
2. Layer thickness	Shape, extent, temporal variation	Incomplete Melting Defects	<u>Physical:</u> Stress
3. Gas flow rates		Residual Stress	Roughness
4. Print pattern		Composition	Porosity
<u>Limited Control:</u>			Defects
1. Powder morphology	Ejection Plume	Microstructure	
2. Layer thickness			
3. Packing density			
4. Composition			
5. Build plate	(IR, thermal imaging, microwave)		

Color Key: In Progress, Planned Implementation, Potential Candidates Identified, Impractical/TBD

BQ Project-Wide *in-process* Efforts: Cameras for melt pool and part geometry characterization and pyrometers for temperature measurements.

Task Objective: Compliment current BQ efforts by utilizing non-destructive characterization tools to obtain quantitative information about solidified material *in-process*.

Proposed Approach

Method 1: Confocal Chromatic White Light Line Sensor

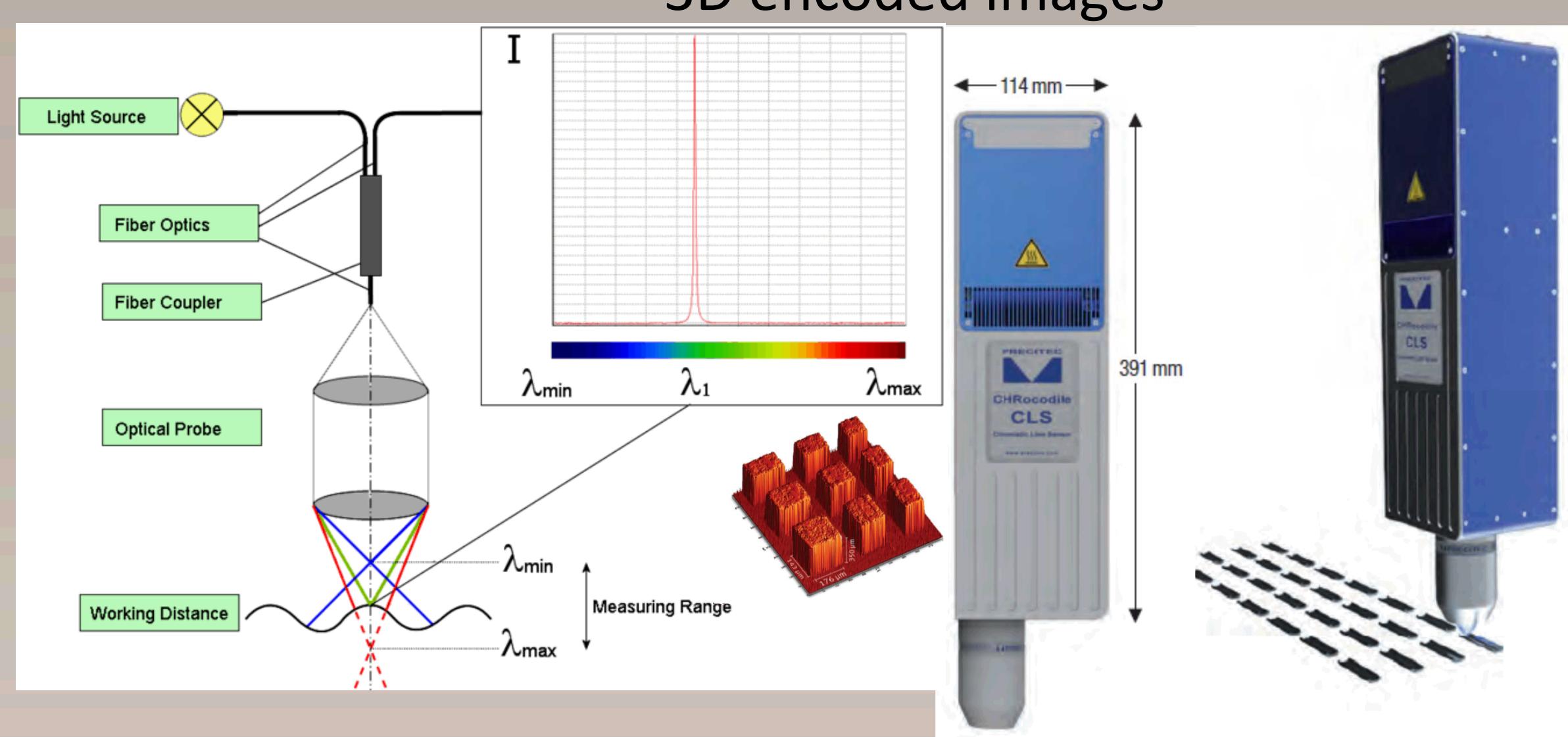
Information Gathered

Layer-by-layer real-time surface roughness, defects and topography
Particle packing density
Geometric dimensions

Advantages

Rapid
Wide focal range
Line and point probes
Small probe size
3D encoded images

May require optical filtering
Temperature sensitivity



Candidate Product: Precitec CLS 1 with CHRocodile Sensor

Probe Specs

Measuring range = 1 mm
Line length = 1.91 ± 0.01 mm
Working distance = 18.5 ± 0.2 mm
Spot size = 4 μ m
Lateral resolution = 2 μ m
Axial resolution = 80 nm

Sensor Specs

Up to 2,000 lines/sec
384,000 data pts/sec
192 data pts/line
LED light source
4 kg mass
Up to 50 °C

Method 2: Eddy Current Array Testing

Information Gathered

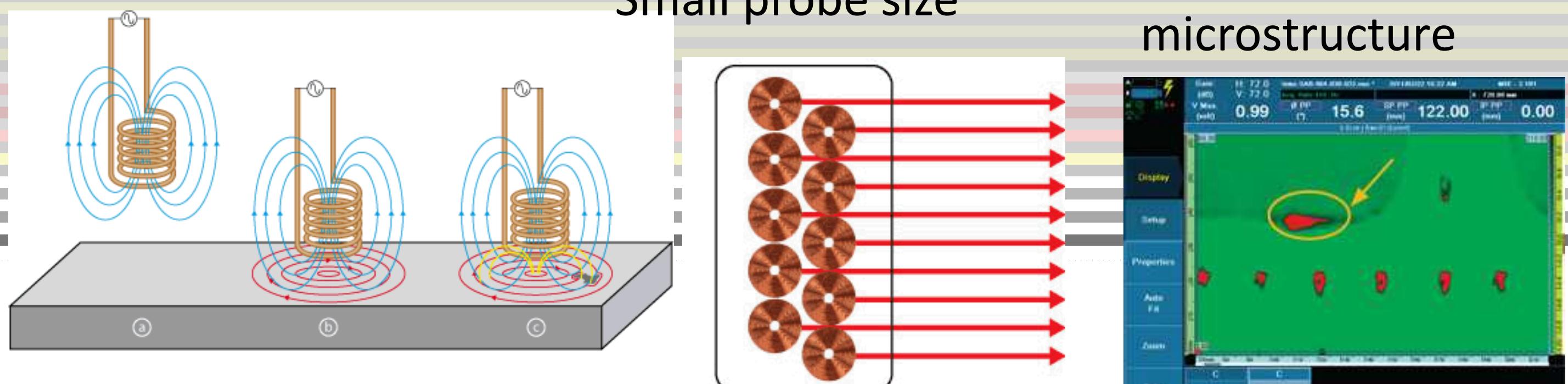
Surface and near-surface microstructural defects, cracks/voids

Advantages

Rapid
Encoded images of defects
Small probe size

Challenges

Close working distance of 50 μ m
Sensitive to surface roughness and microstructure



Candidate Product: Olympus OmniScan MX

Supports conventional ECT, ECA and C-scan
1-4 ECT and 32 ECA channels
Absolute, differential, bridge and reflection modes
Up to 8 testing frequencies from 20 Hz to 6 MHz
Maximum 15 kHz data acquisition

Additional Candidate Methods: Raman and Laser-induced Breakdown Spectroscopy (LIBS), Ultrasonic testing, X-ray diffraction (XRD), X-ray fluorescence (XRF).